

## Specification Sheet for Approved

Customer Name:	
Customer Part No.:	
Ceaiya Part No:	CMPI0530 系列
Spec No:	L0530

**【For Customer Approval Only】**

If you Approval, Please Stamp

**【RoHS Compliant Parts】**

Approved By	Checked By	Prepared By
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## Specification Sheet for SMD Power Inductor

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### 【Version of Changed Record】

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
A0	2020-12-31	New release	Internal changes	Li qin hui

# Specification Sheet for SMD Power Inductor

## 1. Scope

This specification applies to the CMPI0530 Series of wire wound SMD power inductor.

## 2. Product Description and Identification (Part Number)

1) Description:

CMPI0530 series of Wire wound SMD power inductor.

2) Product Identification (Part Number)

CMPI  
①
0530  
②
-
1R0  
③
M  
④

① Product Series

② Choke Size

③ Initial Inductance(L @ 0A):1R0=1.0μH

④ Inductance Tolerance:M=L+/-20%

## 3. Electrical Characteristics

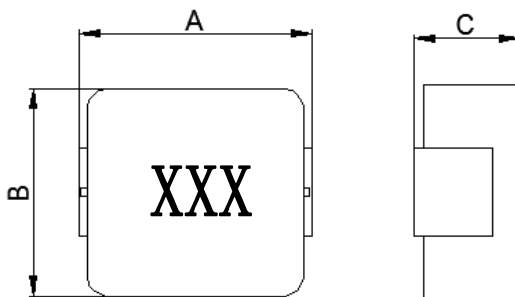
1) Operating temperature range (individual chip without packing): -40°C ~ +125°C (Including Self-heating) .

2) Storage temperature range (On PCB ): -40°C ~ +125°C

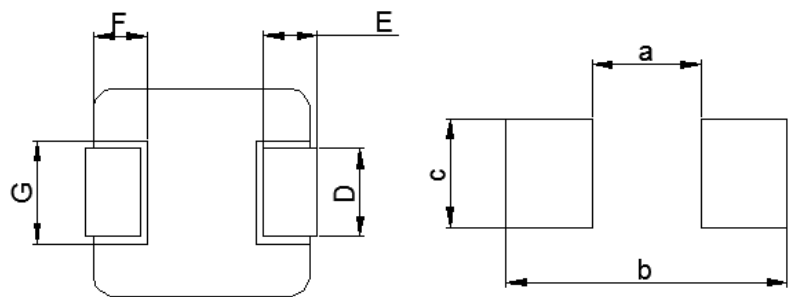
## 4. Shape and Dimensions (Unit:mm)

Dimensions and recommended PCB pattern for reflow soldering, please see

### MECHANICAL PARAMETERS



### RECOMMENDED PCB LAYOUT



A	B	C	D	E	F	G	a	b	c
5.50	5.20	3.00	2.20	1.20	1.50	2.50	2.20	6.00	2.50
±0.30	±0.30	Max	±0.30	±0.30	Typ.	Typ.	Typ.	Typ.	Typ.

### Notes:

1. Marking :Ink Marking
2. Stamping XXX :inductor
3. Dimensions of recommended PCB layout are reference only.
4. Do not route traces nor place vias underneath the inductor. Proper layout is required.

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### 5. Electrical Characteristics

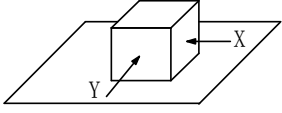
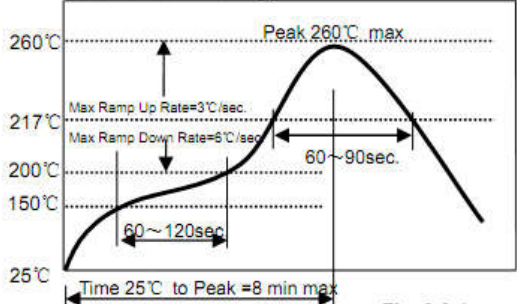
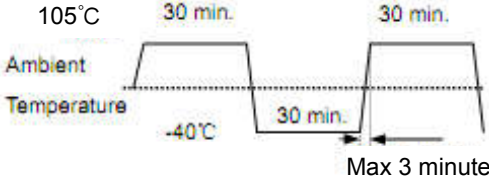
Part Number	L0(uH)	DCR(mΩ) @25°C		Isat(Amp) Typ.	Irms(Amp) Typ.
		Max.	Typ.		
CMPI0530-R10N	0.10±30%	3.0	2.4	33.0	25.0
CMPI0530-R20M	0.20±20%	4.0	3.5	14.5	14.0
CMPI0530-R47M	0.47±20%	8.5	7.4	12.0	11.0
CMPI0530-R68M	0.68±20%	12.0	11.0	11.5	9.0
CMPI0530-1R0M	1.0±20%	15.0	13.0	11.0	8.5
CMPI0530-1R5M	1.5±20%	25.0	20.0	8.5	8.2
CMPI0530-2R2M	2.2±20%	30.0	25.0	7.5	6.0
CMPI0530-3R3M	3.3±20%	40.0	32.0	6.0	5.5
CMPI0530-4R7M	4.7±20%	65.0	50.0	5.0	4.5
CMPI0530-6R8M	6.8±20%	90.0	75	4.0	3.5
CMPI0530-100M	10±20%	126	110	3.5	3.0

**Notes:**

1. Initial Inductance (L0) Test Parameters: 100KHz, 1V, Idc=0.0A, +25°C
2. All test data is referenced to 25°C ambient;
3. Rated current: Isat or Irms, whichever is smaller;
4. Irms(A): DC current that causes the temperature rise ( $\Delta T = 40^\circ \text{C}$ ) from 25° C ambient.
5. Isat(A): DC current at which the inductance drops approximate 30% from its value without current;

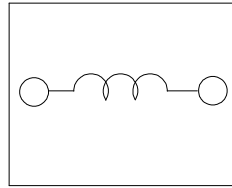
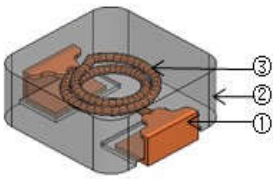
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## 6. Reliability Test

Items	Requirements	Test Methods and Remarks
6.1 Terminal Strength	No removal or split of the termination or other defects shall occur.   Fig.6.1-1	1) Solder the inductor to the testing jig (glass epoxy board shown in Fig.6.1-1) using eutectic solder. Then apply a force in the direction of the arrow. 2) 10N force. 3) Keep time: 5±2s
6.2 High Temperature	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Storage Temperature :125+/-5°C 2) Duration : 96 ±4 Hours 3) Recovery : then measured at room ambient temperature after placing 24 hours.
6.3 Low Temperature	1. No visible mechanical damage 2. Inductance change: Within ±10%	1) Temperature and time: -40±5°C 2) Duration: 96±4 hours 3) TRecovery : then measured at room ambient temperature after placing 24 hours.
6.4 Vibration test	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Frequency range:10HZ~55HZ~10HZ 2) Amplitude:1.5mm p-p 3) Direction:X,Y,Z 4) Time:1 minute/cycle,2hours per axis
6.5 High Temperature Storage Tested	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Storage Temperature :60+/-2°C 2) Relative Humidity :90-95% 3) Duration : 96 ±4 Hours 4) Recovery : then measured at room ambient temperature after placing 24 hours.
6.6 Resistance to Soldering Heat	1. No visible mechanical damage. 2. Inductance change: Within ±10%   Fig.6.6-1	1) Re-flowing Profile: Please refer to Fig.6.6-1 2) Test board thickness: 1.0mm 3) Test board material: glass epoxy resin 4) The chip shall be stabilized at normal condition for 1~2 hours before measuring
6.7 Thermal Shock	1. No visible mechanical damage. 2. Inductance change: Within ±10%   Fig.6.7-1	1) Temperature and time: -40±3°C for 30±3 min→105°C for 30±3min, please refer to Fig.6.7-1. 2) Transforming interval: Max, 3 minute 3) Tested cycle: 100 cycles 4) The chip shall be stabilized at normal condition for 1~2 hours before measuring

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### 7. MATERIAL LIST



NO.	Part Name	Material
1	Electrode	Cu+Sn plating
2	Core	Metal composite core
3	Coil	Copper wire, 220°C

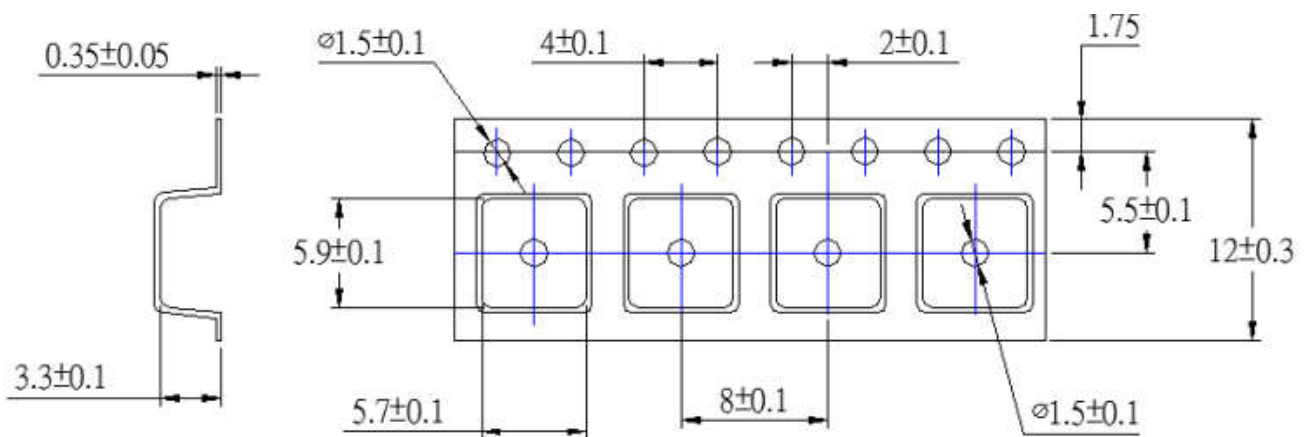
### 8. PACKAGE INFORMATION-mm

#### Peel-off Force

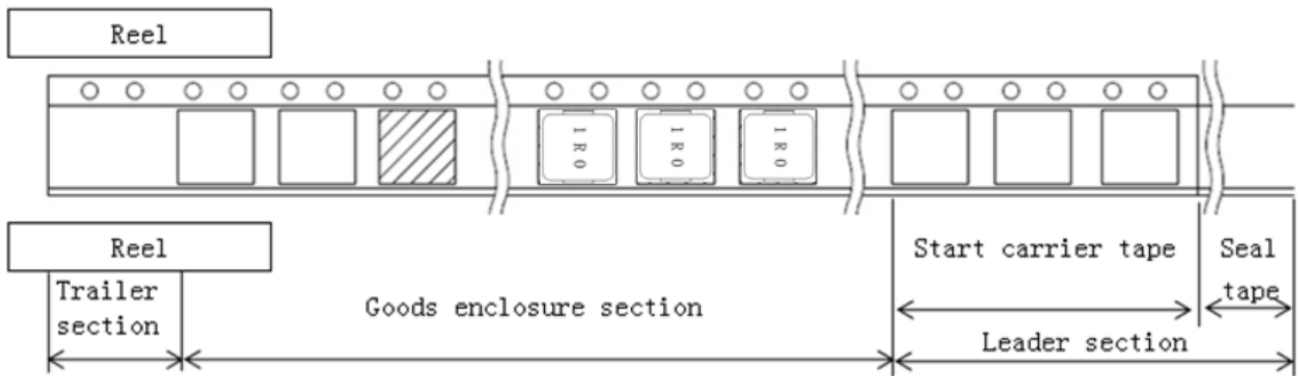


The force for peeling off cover tape is 10 to 70 grams in the arrow direction.

#### 8.1 Tape Packaging Dimensions

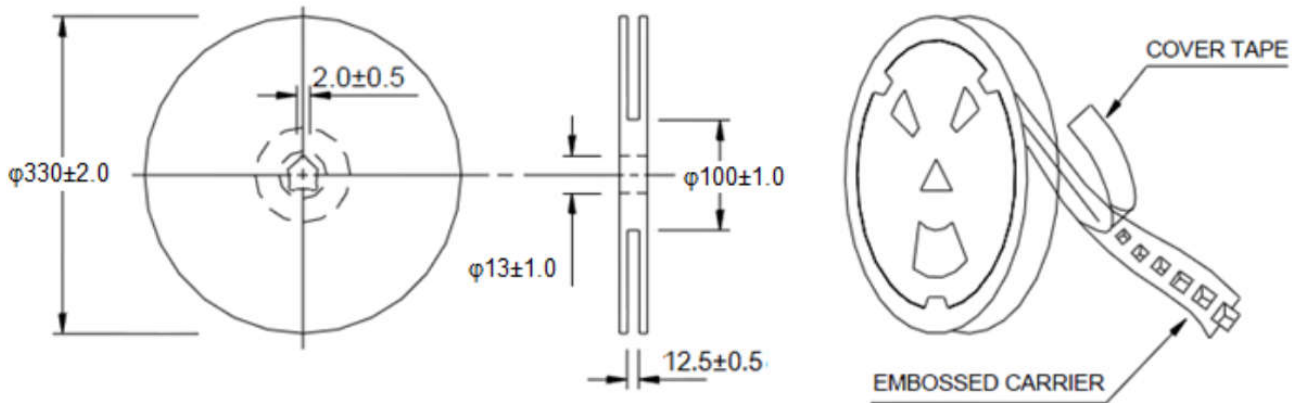


**8.2 Taping dimension and tape direction, Leader ,Trailer, section dimension**



Leader section	Min.400mm
Carrier tape start size	Min.100mm
Trailer section size	Min.160mm

**8.3 Reel Dimensions**



**8.4 Taping Quantity**

2000pieces/Reel,

**8.5 Carton**

Pizza packaging: 3Reel/ Pizza Box

External Packaging :3 Boxes/Carton